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10614744, GAU: 2617

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	Filing Date		2003-07-07
	First Named Inventor	John A. Hicks III	
	Art Unit	2617	
	Examiner Name	Chuck Huynh	
	Attorney Docket Number	BS02500/ATTWP292US	

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	4	7502615		2009-03-10	Wilhoite, et al.	
	5	7466991		2008-12-16	Everson, et al.	
	6	7406324		2008-07-29	Von, K. McConnell	
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